

Features

- high rejection
- Flat group delay @ passband
- good VSWR, 1.2:1 typ @ passband
- shielded case
- aqueous washable

Applications

- radio link
- receivers / transmitters
- harmonic rejection

HT-SXBP-350+



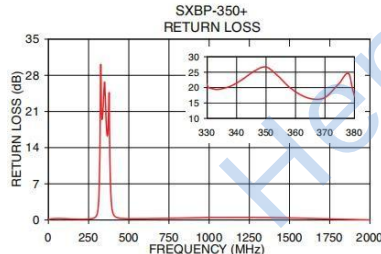
50Ω 330 to 375 MHz

Bandpass Filter Electrical Specifications (T_{AMB}= 25°C)

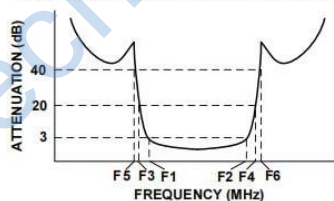
CENTER FREQ. (MHz)	PASSBAND (MHz) (Loss < 3dB)	STOPBAND (MHz)				VSWR		
		(Loss > 20dB)		(Loss > 40dB)		Passband		Stopband
F _c	F1 - F2	F3	F4	F5	F6	Typ.	Max.	Typ.
350	330-375	280	435	245	520-2000	1.2	1.5	20

Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)		Return Loss (dB)	Frequency (MHz)	Group Delay (nsec)
	×	σ			
0.5	77.48	2.27	0.24	330.0	16.58
245.0	51.21	0.45	0.22	332.0	15.81
280.0	32.44	0.51	0.29	334.0	15.15
300.0	17.62	0.71	1.01	338.0	14.32
300.0	8.62	0.78	3.07	342.0	13.74
310.0	4.82	0.59	6.57	346.0	13.33
320.0	2.74	0.32	15.40	350.0	13.10
330.0	1.89	0.19	17.22	354.0	12.98
342.0	1.69	0.20	22.55	355.0	12.96
350.0	1.69	0.19	26.48	358.0	12.91
366.0	1.87	0.19	19.67	362.0	12.89
375.0	2.09	0.18	23.06	366.0	13.20
385.0	4.07	0.24	11.76	370.0	13.78
392.0	7.99	0.31	5.74	375.0	15.23
405.0	16.28	0.29	2.56	378.0	16.30
435.0	30.23	0.18	1.21	380.0	16.90
520.0	50.91	0.07	0.55	385.0	17.12
2000.0	56.91	0.26	0.35	390.0	15.07



Typical Frequency Response

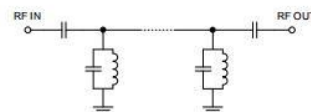


Maximum Ratings

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power Input*	0.5W max.

Permanent damage may occur if any of these limits are exceeded.

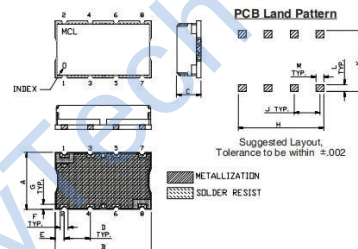
Functional Schematic



Pad Connections

INPUT	1
OUTPUT	8
GROUND	2,3,4,5,6,7

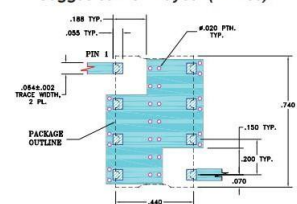
Outline Drawing



Outline Dimensions: Unit (mm)

A	11.18	D	5.08	G	1.02
B	18.80	E	1.78	H	16.76
C	6.86	F	1.52	J	5.08
L	1.40	M	1.52	K	11.94
wt					3.0

Demo Board MCL P/N: TB-368
Suggested PCB Layout (PL-230)



NOTE:
1. TRACE WIDTH IS SHOWN FOR FR4 WITH DIELECTRIC THICKNESS: .005" (127μm). COPPER: 1/2 OZ. EACH SIDE.
FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
3. DENOTES PCB COPPER LAYOUT WITH SMDs (SOLDER MASK OVER BARE COPPER)
4. DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK